90 74 5								R	EVIS	NOI	IS												
LTR				C	DESC	CRIP	TION	1								DAT	TE (YI	R-MO	-DA)	-	APPF	ROVE	D
															Ţ	-	日マ	1W	T W	07	5	3.0	0
				.0.																			
	库	电火	NW	.0	25	C-	6.0										日	3-	TW	11	5	70 C	0
REV	库	E WY	NW	.0	15	G -	6.0		I		3,8						一日	, w	3 W	11	5	7. c	I
REV SHEET	库 H	E WY	NW	.0	15	G -	6.0				3.0						E		7 W	07	5	7. C	
	库	起が	NW	0,0	15	6-	000				3.0						日	a. W	3	07	150	70 C	
SHEET	I I	EWY A	N WI	0	15	6	C0				3,4				V		E	3.	J.W.	11.07	150	3	
SHEET REV SHEET REV STATUS	REV	E WY	NW	0.	15	6	C.0	3			3,2						E	a W	J.W.	1	50	3) c	
SHEET REV SHEET	REV		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15		17	18	150	3) c	
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STANDARI	SHEET		1 PREBA	2 ARED.	3) BY 6- 4 BY	4		6		<u> </u>	9	10		12 ENSE	E ELE		ONIC	16	17 UPPI	18 Y CE			
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	SHEET DIZED RY		1 PREBA	2 ARED KED	3 3 BY	4		6		<u> </u>		ICR	DEF	ENSE	DAY	CTR	ONIC I, OH	16 CS SI AD	17 UPPI 5444	18 Y CE	CMOS	R C	
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STANDARI MILITA	SHEET DIZED RY NG AVAILABLE EPARTMENT S OF THE	TS.	1 CHECK	2 ARED OVER SING 13	3 BY APPI	4 Rov	5 total	6 Cell		<u> </u>	- M U	ICR	DEF	RCUI' BIN/	DAY	IGIT COUN	ONIC I, OH	16 SS SI AD'	17 UPPI 5444 VANC	18 LY CED (ITH:	CMOS	R	OI

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5962-E1435

1. SCOPE	-				
1.1 Scope. This drawing describes device ith 1.2.1 of MIL-STD-883, "Provisions for on-JAN devices".	ce require the use o	ments f MIL-	for class B m STD-883 in co	icrocircuit njunction w	ts in accordance with compliant
1.2 Part number. The complete part number	ber shall	be as	shown in the	following e	example:
5962-89749 01			E - - 		X -
1.2.1 Device type. The device type shall	ll identif	y the	circuit funct	ion as foll	lows:
Device type Generic number			Circui	t function	
01 54AC191	Up/	down b	inary counter	with prese	et and ripple clock
1.2.2 <u>Case outlines</u> . The case outlines s follows:	shall be	as des	ignated in ap	pendix C of	f MIL-M-38510, and
Outline letter			e outline		
E D-2 (16-lead F F-5 (16-lead 2 C-2 (20-tern	d, .840" x d, .440" x minal, .35	.310" .285" 8" x .	x .200"), du x .085"), fl 358" x .100")	al-in-line at package , square cl	package hip carrier package
1.3 Absolute maximum ratings.					
Supply voltage range $1/$ DC input voltage $1/$ DC output voltage $1/$ DC output voltage $1/$ DC output current (per pin) DC v _{CC} or GND current Storage temperature range Maximum power dissipation (P_D) Lead temperature (soldering, 10 secon Thermal resistance, junction-to-case Junction temperature (T_J) $1/$ 2/	nds)		-0.5 V dc t -0.5 V dc t ±20 mA ±50 mA ±100 mA -65 C to +1 500 mW +300 C	o V _{CC} + 0.1	5 V dc 5 V dc
1.4 Recommended operating conditions.					
Supply voltage range (V_{CC}) $3/$ Input voltage range Output voltage range Case operating temperature range (T_{C} Input rise or fall times: V_{CC} = 3.6 V to 5.5 V			U.U V ac to	VCC VCC 25°C	С
/ Unless otherwise specified, all voltage / Maximum junction temperature shall not screening conditions in accordance wit / Operation from 2.0 V dc to 3.0 V dc is battery backup systems. Data retention with the following conditions: V _{IH} > V _{OH} > 70 percent V _{CC} at -20 μA, V _{OL} ≤	be exceed h method 5 provided n implies	led exc 004 of for co	cept for allow f MIL-STD-883. ompatibility w out transition	rith data re	etention and
STANDARDIZED MILITARY DRAWING	SIZE A		REVISION LEVE	L	5962-89749
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2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the Issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103

- List of Standardized Military Drawing (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Truth tables. The truth tables shall be as specified on figure 2.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

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- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 Verification and review. DESC, DESC'S agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procesures shall be in accordance with section $\frac{4}{4}$ of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 (CIN and Cpp measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Test all applicable pins on five devices with zero failures.
 - d. Subgroup 7 and 8 tests shall verify the truth table as specified on figure 2.

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		I. Electr				I		
Test	Symbol	i I unle	Condit 55°C < T _C	±125°C se specified	Group A	<u>Lim</u>	its	Unit
	<u> </u>		33 Otherwis	se specified	Subgroups	Min	Max	
High level output voltage	i v _{OH}	V _{IN} = V _{IH} or V _{IL} max I _{OH} = -50	minimum imum,	V _{CC} = 3.0 V	1, 2, 3	2.9		V
		 -0H = -30	<u>1</u> /	V _{CC} = 4.5 V	<u> </u>	4.4		_
		 		V _{CC} = 5.5 V		5.4		_
		 V _{IN} = V _{IH}	minimum imum, nA <u>1</u> /	V _{CC} = 3.0 V		2.4		-
		 V _{IN} = V _{IH} max	ninimum imum,	V _{CC} = 4.5 V		3.7		•
		I _{OH} = -24 m	nA <u>1</u> /	V _{CC} = 5.5 V		4.7		-
	 	 VIN = VIH	ninimum imum, nA <u>1</u> /	V _{CC} = 5.5 V		3.85		•
Low level output voltage	VOL	 VIN = VIH n or VIL max1 I _{OL} = 50 µA	ninimum mum,	V _{CC} = 3.0 V	1, 2, 3		0.1	٧
	! 	 1 ₀ = 50 με	1/	V _{CC} = 4.5 V		1	0.1	•
				V _{CC} = 5.5 V			0.1	
		VIN = VIH m or VIL maxi I _{OL} = 12 mA	ninimum mum, <u>1</u> /	V _{CC} = 3.0 V		1	0.5	
		V _{IN} = V _{IH} m or V _{IL} maxi I _{OL} = 24 mA	inimum mum,	V _{CC} = 4.5 V	† † ! !		0.5	
	 <u> </u>	1 _{OL} = 24 mA	1/	V _{CC} = 5.5 V	T T		0.5	
		V _{IN} = V _{IH} m or V _{IL} maxi I _{OL} = 50 mA	inimum mum, $\frac{1}{}$	V _{CC} = 5.5 V			1.65	
See footnotes at end	of table.	***************************************				1		
STANDAF MILITARY D		G	SIZE A			5962-8	9749	
DEFENSE ELECTRON DAYTON, O	ICS SUPPLY			REVISION LE	VEL	SHEE	T	

TABLE I. Electrical performance characteristics - Continued. Conditions $-55^{\circ}\text{C} < \text{T}_{\text{C}} < +125^{\circ}\text{C}$ unless otherwise specified Symbol 3 Test Group A Limits Unit subgroups Min Max |¥IH High level input VCC = 3.0 V 1, 2, 3 2.1 voltage 2/ $V_{CC} = 4.5 \text{ V}$ 3.15 V_{CC} = 5.5 V 3.85 Low level input voltage VIL $V_{CC} = 3.0 V$ 1, 2, 3 0.9 2/ $V_{CC} = 4.5 \text{ V}$ 1.35 $V_{CC} = 5.5 \text{ V}$ 1.65 V_{CC} = 5.5 V μΑ Input leakage YIN = 0.0 Y 1, 2, 3 -1.0 IIL current V_{IN} = 5.5 V 1.0 I_{IH} $V_{CC} = V_{CC} \text{ or GND,}$ 1, 2, 3 $\mu \boldsymbol{A}$ Quiescent current 160 ICCH ICCL 160 1160 ICCZ 4 рF Input capacitance CIN See 4.3.1c 8.0 Power dissipation CPD |See 4.3.1c 4 85 рF capacitance 3/ Functional tests |Tested at $V_{CC} = 3.0$ V and repeated | lat $V_{CC} = 5.5$ V, |see 4.3.1d 7,8

See footnotes at end of table.

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Т	ABLE I. <u>E</u>	lectrical p	erformance	chara	cteristics	- Continued			
Test	Symbol	-5 unles	Condi 5°C < T _C s otherwi	< +125	°C cified	Group A subgroups	Lim Min	its	Unit
Propagation delay time, CP to Qn	tPHL1	C _L = 50 pF R _L = 500Ω, see figure		V _C	C = 3.0 V	9 10,11	1.0 1.0	13.0 16.0	ns
		4/		V _C	C = 4.5 V	9 10,11	1.5 1.5	10.0 12.0	
	t _{PLH1}			V _C	C = 3.0 V	9 10,11 	1.0 1.0	 13.0 16.5	ns
				ν _C	C = 4.5 V	9 1	1.5 1.5	 10.0 12.0	
Propagation delay time, CP to TC	t _{PHL2}			VC	C = 3.0 V	9 10,11	1.0	15.5 19.0	ns
				V _C	C = 4.5 V	9 10,11	1.5 1.5	 11.5 14.5	
	t _{PLH2}			VC	C = 3.0 V	9 9 10,11	1.0 1.0	 15.0 19.5 	ns
				VC	c = 4.5 V	9 10,11	1.5 1.5	11.0 11.0 14.0	
Propagation delay time, CP to RC	t _{PHL3}			v _C	C = 3.0 V	9 10,11 	1.0 1.0	10.0 12.5	ns
				V _C	C = 4.5 V	9 10,11	1.5 1.5	8.0 9.5	:
	t _{PLH3}			V _C	C = 3.0 V	9 10,11	1.0 1.0	11.5 14.0	ns
	 			VC	c = 4.5 V	9 9 10,11	1.5 1.5	9.0 9.0 10.5	
See footnotes at end	l of table.		-						
STANDAI MILITARY I		·C	SIZE A				5962-8	0740	
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Test	Symbol	 -55	Condit 5°C < T _C <	+125	С	Group A	<u>Lim</u>	its	Unit
		l unless	otherwis	e spec	ified	subgroups	Min	Max	
Propagation delay time, CE to RC	t _{PHL4}	C _L = 50 pF, R _L = 500Ω, see figure	4	V _{CC}	= 3.0 V	9 10,11	1.0	10.5 12.5	ns
		<u>4</u> / 		Vcc	= 4.5 V	9 10,11	1.5 1.5	7.5 9.5	
	t _{PLH4}	1		v _C c	= 3.0 V	9 10,11	1.0 1.0	11.5 14.0	ns
				VCC	= 4.5 Y	9 10,11	1.5 1.5	8.0 10.0	
Propagation delay time, U/D to RC	tpHL5	 - -		VCC	= 3.0 V	9 10,11	1.0	12.5 15.0	ns
	 			VCC	= 4.5 V	9 10,11	1.5 1.5	9.0 11.0	
	t _{PLH5}			VCC	= 3.0 V	9 10,11	1.0	12.5 14.5	ns
] 	 		V _{CC}	; = 4.5 V	9 10,11	1.5 1.5	9.0 9.0 11.0	 <u>-</u>
Propagation delay time, U/D to TC	t _{PHL6}	! ! !		VCC	; = 3.0 V	9 10,11	1.0 1.0	11.0	ns
	 			V _C C	; = 4.5 V	9 10,11	1.5 1.5	8.5 10.0	
	t _{PLH6}] 		V _C (; = 3.0 V	9 10,11	1.0	11.0	ns
	 	 		VC	= 4.5 V	9 10,11	1.5 1.5	8.5	
See footnotes at end	i of table	•		· ·					
STANDAI MILITARY I		NG.	SIZE A				5962-8	9749	
						SION LEVEL SHEET			

Т	ABLE I. E			characteristics	- Continued			
Test	Symbo1	-5	Condi 5°C < T _C	tions <pre>tions +125°C se specified</pre>	Group A	Lim	its	Unit
		unles	s otherwis	se specified	subgroups	Min	Max	
Propagation delay time, Pn to Qn	t _{PHL} 7	 C _L = 50 pF R _L = 500Ω, see figure		V _{CC} = 3.0 V	9 1 10,11	1.0 1.0 1.0		l ns
		<u>4</u> / 		V _{CC} = 4.5 V	9 10,11	1.5 1.5	9.0 10.5] [] [
	t _{PLH7}			V _{CC} = 3.0 V	9 10,11	1.0	13.5 16.5	ns
				Y _{CC} = 4.5 V	9 10,11	1.5	9.0 11.5	
Propagation delay time, PL to Qn	t _{PHL8}	 		V _{CC} = 3.0 V	9 10,11	1.0	12.5 15.5	ns
				V _{CC} = 4.5 V	9 10,11	1.5 1.5	 9.5 11.5 	
	t _{PLH8}			V _{CC} = 3.0 V	9 10,11	1.0	14.0 18.0	ns
				V _{CC} = 4.5 V	9 10,11	1.5 1.5	10.0 12.5	
Maximum clock frequency, CP	f _{MAX}			V _{CC} = 3.0 V	9 10,11	70 55] 	 MHz
				V _{CC} = 4.5 V	9 10,11	90 80]]]	
Setup time, Pn to PE (high or low)	t _{s1}			V _{CC} = 3.0 V	9 10,11	3.5 4.0		ns
				V _{CC} = 4.5 V	9 10,11	2.5 3.0	 	
See footnotes at end	d of table.							
STANDAI MILITARY I		IG	SIZE A			5962-89	9749	
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Test	Symbol	Condit -55°C <u><</u> T _{C ≤}	+125°C	Group A	Limi	its	Unit
	<u> </u>	unless otherwis	se specified	subgroups	Min	Max	
Setup time, CE to CP (low)	t _{s2}	 C _L = 50 pF, R _L = 500Ω, see figure 4	V _{CC} = 3.0 V	9 10,11	7.0 9.0		l ns
	 	<u>4</u> / 	V _{CC} = 4.5 V	9 10,11	5.0 6.0		
Setup time, U/D to CP (high or low)	t _{\$3}	 	V _{CC} = 3.0 V	9 10,11	9.0 10.5	 	ns
			V _{CC} = 4.5 V	9 10,11	6,0 7.5		1 1 1
Hold time, Pn to PE (high or low)	t _{h1}	 	Y _{CC} = 3.0 V	9 10,11	1.0 1.5		ns
	 -	 - 	Y _{CC} = 4.5 V	9 10,11	2.0	 	1
Hold time, CE to CP (low)	t _{h2}	 	V _{CC} = 3.0 V	9 10,11	0.0	[] 	ns
] 	 	Y _{CC} = 4.5 V	9 10,11	0.5 0.5	 	! ! !
Hold time, U/D to CP (high or low)	t _{h3}	 	Y _{CC} = 3.0 V	9 10,11	0.0		ns
		† - -	Y _{CC} = 4.5 V	9 10,11	1.0 1.0		
CP pulse width (high)	t _{w1}	 	Y _{CC} = 3.0 V	9 10,11	5.0 5.0	 	ns
		 	V _{CC} = 4.5 V	9 10,11	5.0 5.0	 	
See footnotes at end	l of table	,					
STANDA	RDIZED	SIZE A					· · · · · · · · · · · · · · · · · · ·

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REVISION LEVEL

	TABLE I. E	lectrical performar	nce characteristics	- Continued	•		
Test	Symbol	Con -55°C < T unless other	Group A Limits				
					Min	Max	<u>i</u>
CP pulse width (low)	t _{w2}	C _L = 50 pF, R _L = 500Ω, see figure 4	V _{CC} = 3.0 V	9 10,11	5.0 6.0	 	l ns
		<u>4</u> / 	V _{CC} = 4.5 V	9 10,11	6.0 6.0	 	
PC pulse width (low)	t _{w3}	 	V _{CC} = 3.0 V	9 10,11	5.0 5.0		ns
			V _{CC} = 4.5 V	9 10,11	5.0 5.0	 	
Recovery time, PE to CP	 t _{rec} 	 	V _{CC} = 3.0 V	9 10,11	1.0 1.5		ns
			V _{CC} = 4.5 V	9 10,11	1.0		1

- $\frac{1}{2}$ The V_{OH} and V_{OL} tests will be tested at V_{CC} = 3.0 V and V_{CC} = 4.5 V. V_{OH} and V_{OL} are guaranteed, if not tested, for V_{CC} = 5.5 V. Limits shown apply to operation at V_{CC} = 3.3 V \pm 0.3 V and V_{CC} = 5.0 V \pm 0.5 V. Transmission driving tests are performed at V_{CC} = 5.5 V with a 2 ms duration maximum.
- $\underline{2}/$ The V_{IH} and V_{IL} tests are not required and shall be applied as forcing functions for the V_{OH} and V_{OL} tests.
- $\frac{3/}{P_D}$ Power dissipation capacitance (Cpp), determines the dynamic power consumption, $P_D = (C_{PD} + C_L)(V_{CC} \times V_{CC})f + I_{CC}(V_{CC})$, and the dynamic current consumption (I_S), is $I_S = (C_{PD} + C_L) \ V_{CC} \ f + I_{CC}$.
- $\frac{4}{V_{CC}}$ AC limits at $V_{CC}=5.5$ V are equal to limits at $V_{CC}=4.5$ V and quaranteed by testing at $V_{CC}=4.5$ V. Minimum ac limits are guaranteed for $V_{CC}=5.5$ V by guardbanding $V_{CC}=4.5$ V limits to 1.5 ns (minimum).
- 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Device type	01	
Case outlines	E and F	2
Terminal number	Termin symbo	
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	P1	NC P1 Q1 Q0 CE NC U/D Q2 Q3 GND NC P3 PC TC RC CP PO VCC

NC = No connection

FIGURE 1. Terminal connections.

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Mode select table

Inputs				Mode
PL	CE	Ū/D	l CP	
 H H L	 L X H	L H X X		Count up Count down Preset (asynchronous) No change (hold)

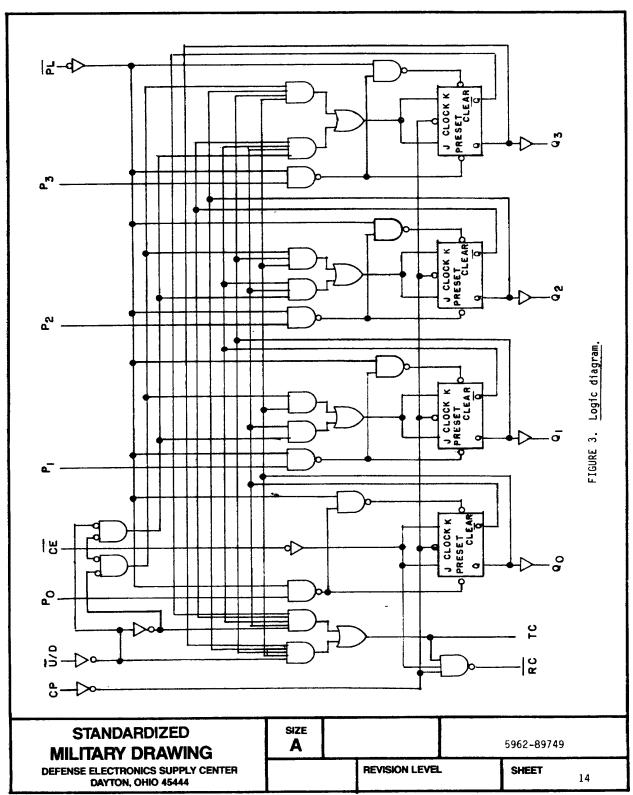
$\overline{\text{RC}}$ truth table

 	Inputs		Outputs
I CE	 TC*	CP	RC
l L l H l X	 H X L	X X	7.f H H

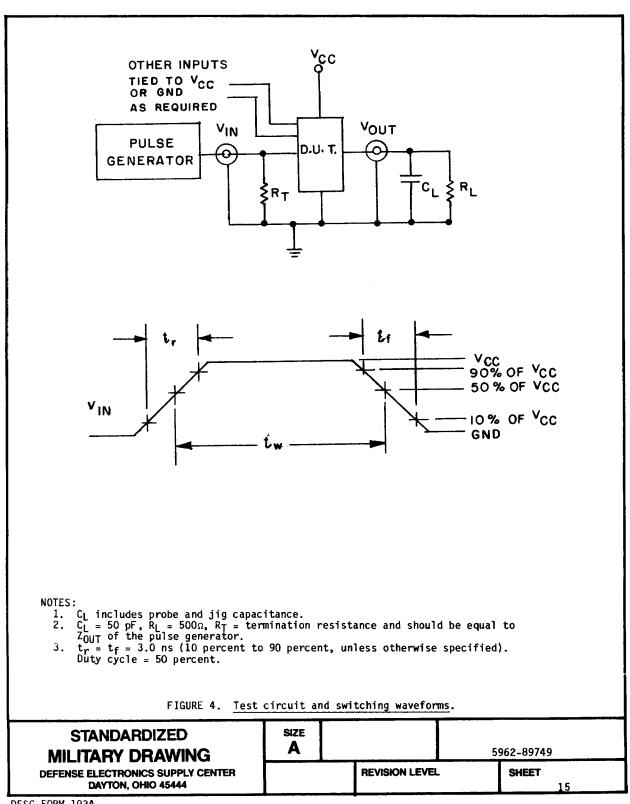
* TC is generated internally
H = High voltage level
L = Low voltage level
X = Irrelevant
† = Low-to-high transition
LF = Low clock pulse

FIGURE 2. Truth tables.

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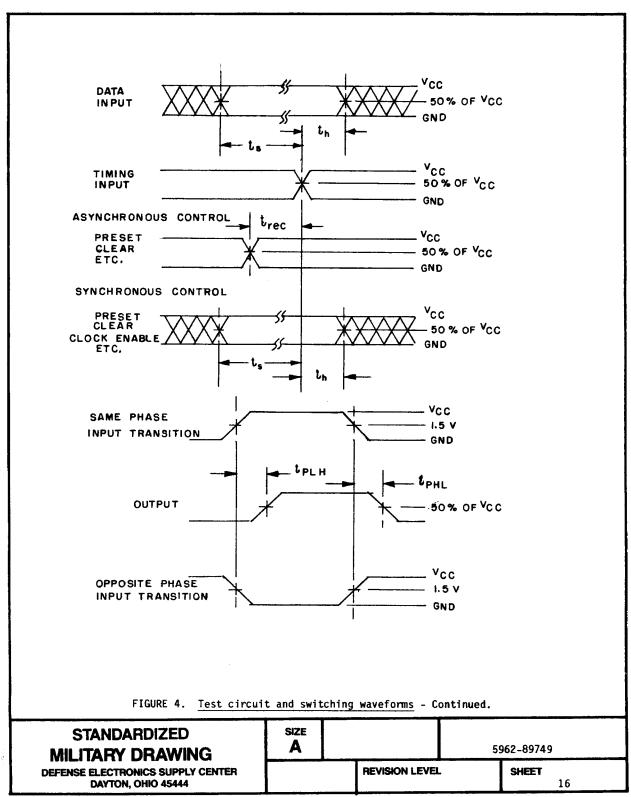


TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)	
Interim electrical parameters (method 5004)		
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9	
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10, 11	
Groups C and D end-point electrical parameters (method 5005)	1,2,3	

*PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-8527.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.6 Approved source of supply. An approved source of supply is listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendor listed in MIL-BUL-103 has agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved source of supply listed below is for information purposes only and is current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
5962-8974901EX	27014	54AC191DMQB
5962-8974901FX	27014	54AC191FMQB
5962-89749012X	27014	54AC191LMQB

 $\frac{1}{acquisition}. \ \ Do \ not \ use \ this \ number \ for \ item \\ \frac{acquisition.}{acquisition}. \ \ Items \ acquired \ to \ this \ number \\ may \ not \ satisfy \ the \ performance \ requirements \\ of \ this \ drawing.$

Vendor CAGE number 27014 Vendor name and address

National Semiconductor 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090

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